

Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. KLA1P016F	Application No.: 09/648,095
	Applicant: Satya, et al	Group 2858
Filing Date August 25, 2000		

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
QVU	A1	5,959,459	9-28-99	Satya et al.	324	751	12-10-96
QVU	A2	6,021,214	2-1-00	Evans et al.	382	141	9-7-95
QVU	A3	5,537,669	7-16-96	Evans et al.	382	141	9-30-93
QVU	A4	4,644,172	2-17-87	Sandland et al.	250	548	2-22-84
QVU	A5	5,502,306	3-26-96	Meisburger et al.	250	310	3-17-94
QVU	A6	5,578,821	11-26-96	Meisburger et al.	250	310	1-11-95
QVU	A7	5,665,968	9-9-97	Meisburger et al.	250	310	2-26-96
QVU	A8	5,717,204	2-10-98	Meisburger et al.	250	310	2-26-96

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
QVU	B1	0 853 243 A2	7-15-98	EPO	G01R	31/307	X	
QVU	B2	0 892 275 A2	1-20-99	EPO	G01R	31/305	X	
QVU	B3	WO 99/22310	5-6-99	WIPO	G06F	17/00	X	
QVU	B4	WO 99/22311	5-6-99	WIPO	G06F	17/00	X	

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
QVU	C1	Tugbawa, et al, "Pattern And Process Dependencies In Copper Damascene Chemical Mechanical Polishing Processes," June 1998, VLSI Multilevel Interconnect conference (VMIC)
QVU	C2	Park et al, "Multi-Level Pattern Effects In Copper CMP," Oct 1999, CMP Symposium Electrochemical Society Meeting
	C3	
Examiner <i>Quynh</i>		Date Considered 10/31/02

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.